

SID

Factory: Rot am See

Article:

553

ML8

Provided:

Kracht, Enrico

Customer:

Date:

29.09.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	220		2
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		3
A-RS-FR4-ML-0.71mm-018+018-TG150-HF	50200793	18	L2	4 A01
		710		
		18	L3	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	210		5
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		6
A-RS-FR4-ML-0.71mm-018+018-TG150-HF	50200793	18	L4	7 A02
		710		
		18	L5	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	210		8
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		9
A-RS-FR4-ML-0.71mm-018+018-TG135	50200371	18	L6	10 A03
		710		
		18	L7	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	220		11
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		12
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	13

Thickness after Pressing

B00:

3090 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3410 µm

Dmin:

2770 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

3200 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3520 µm

Dmin:

2880 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

3134 µm

Version 1.2.14.15

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